

[54] **MODULE FOR HIGH-POWER ELECTRIC CIRCUIT COMPONENTS**

[75] Inventor: **Robert Pintell, New City, N.Y.**

[73] Assignee: **Interelectronics Corporation, Congers, N.Y.**

[**] Term: **14 Years**

[21] Appl. No.: **705,109**

[22] Filed: **Jul. 14, 1976**

[51] Int. Cl. **D13—02**

[52] U.S. Cl. **D13/4; 174/52 R**

[58] Field of Search **D13/4; 174/52 R; 336/59, 90**

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 210,130	2/1968	Stewart	D13/4
D. 212,363	10/1968	Moore	D13/4
D. 212,364	10/1968	Moore	D13/4
D. 227,909	7/1973	Griffing	D13/4
1,669,119	5/1928	Bliss	D13/4 X
2,467,377	4/1949	Giegerich et al.	336/59

Primary Examiner—Bernard Ansher
Attorney, Agent, or Firm—Karl F. Ross

[57] **CLAIM**

The ornamental design for a module for high-power electric circuit components, as shown.

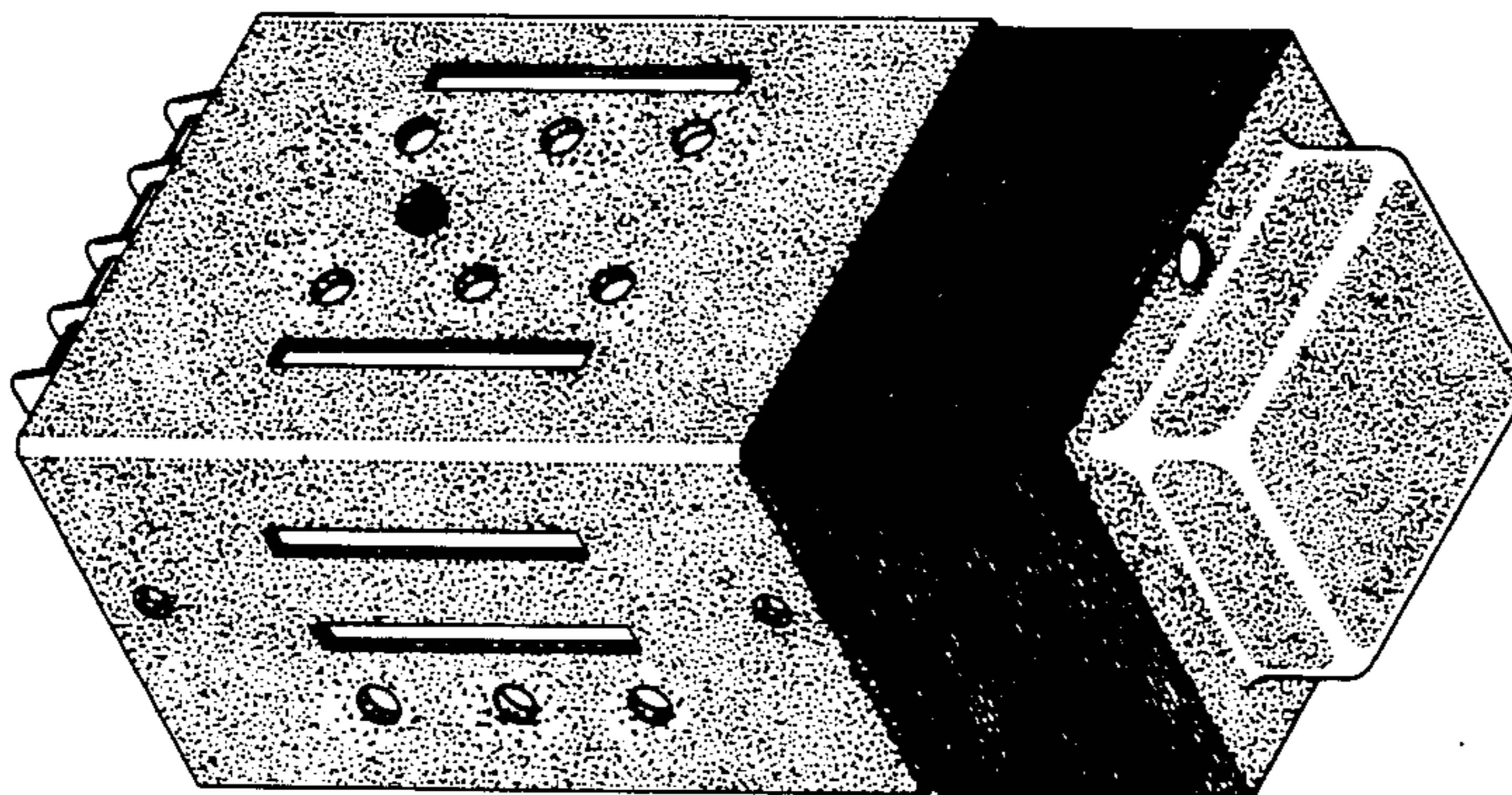
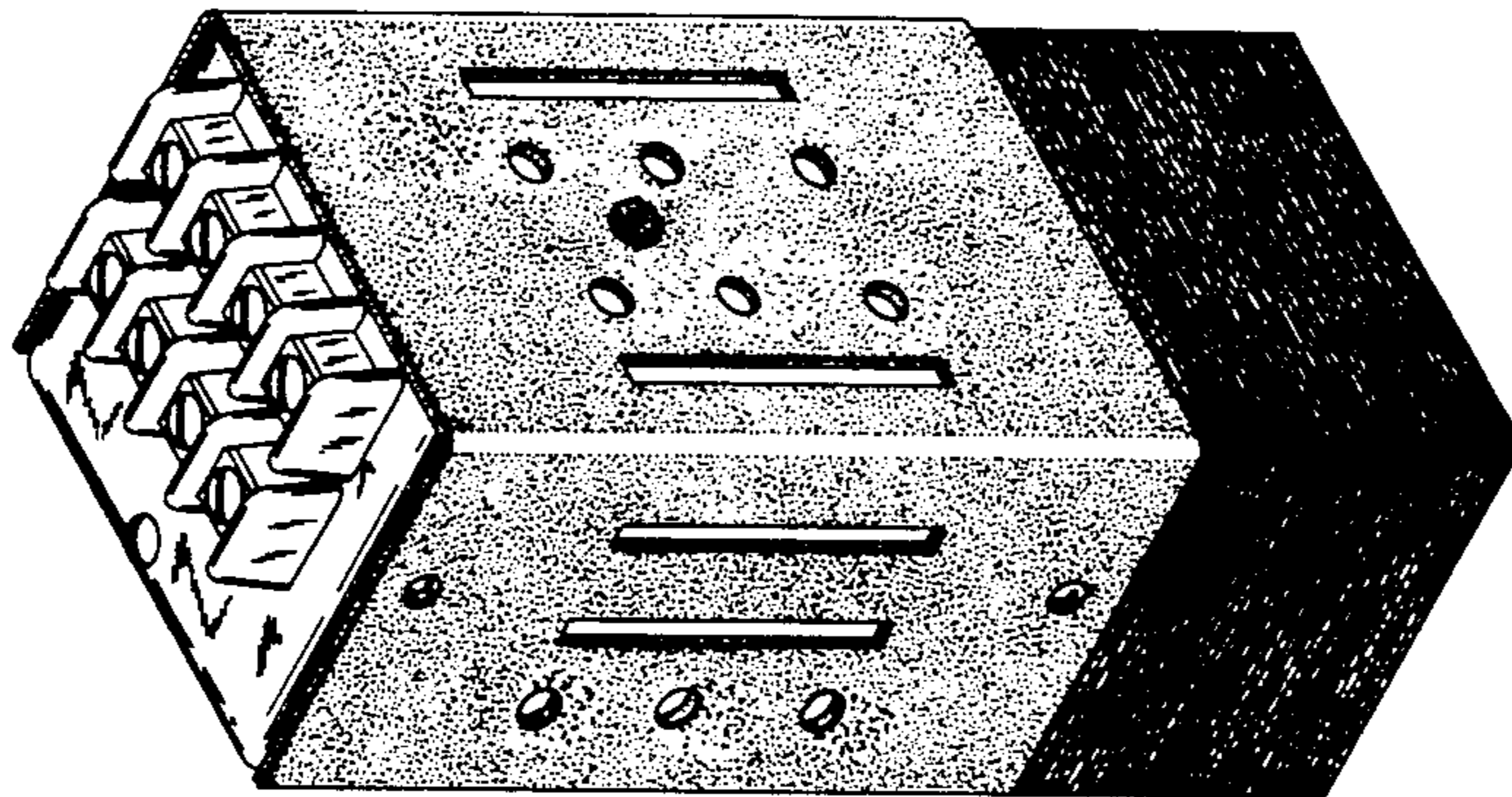
DESCRIPTION

FIG. 1 is a top front perspective view of a module for high-power electric circuit components, showing my new design;

FIG. 2 is a top rear perspective view thereof;

FIG. 3 is a bottom front perspective view thereof; and

FIG. 4 is a bottom rear perspective view thereof.



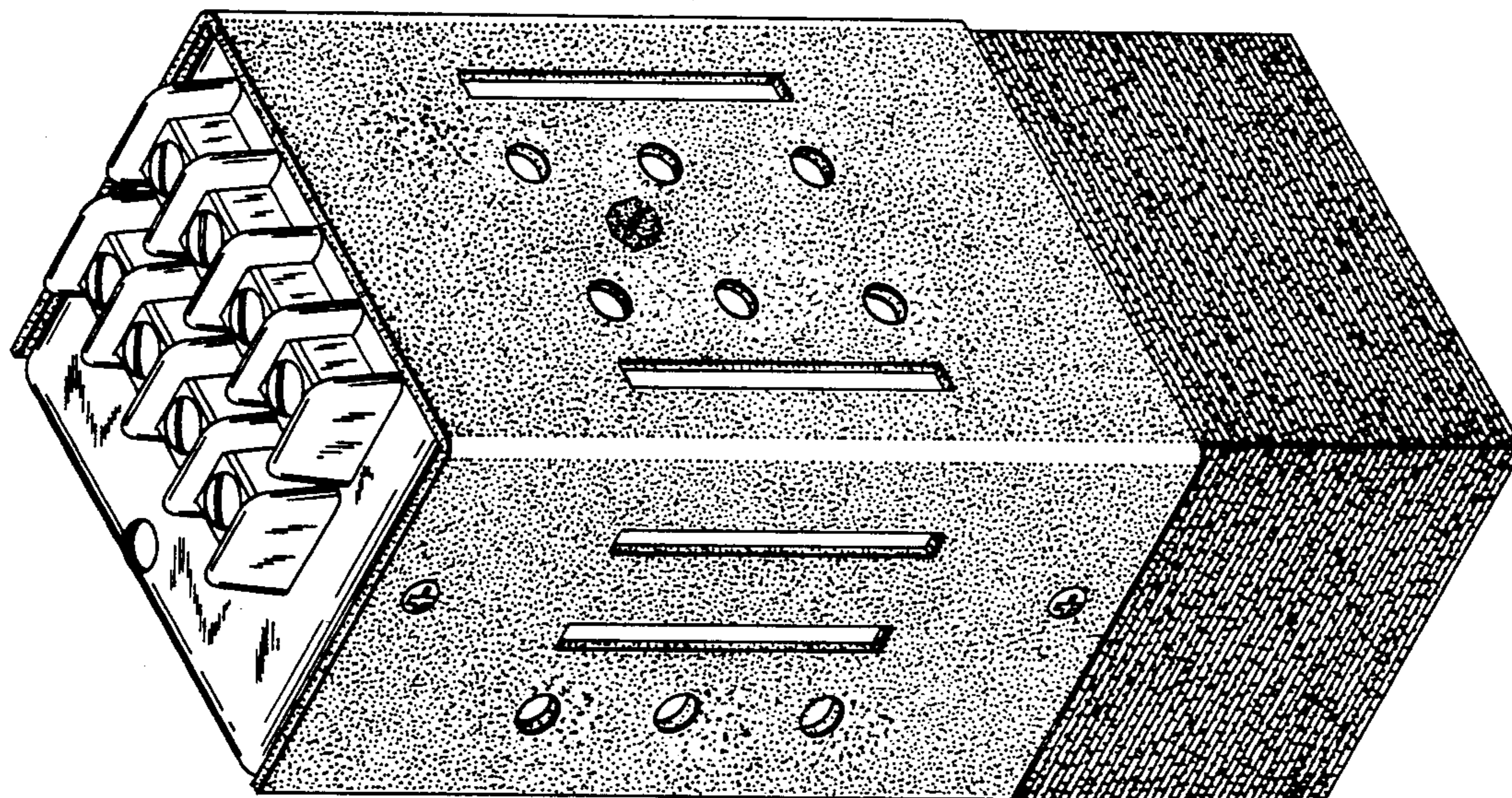


FIG. 1

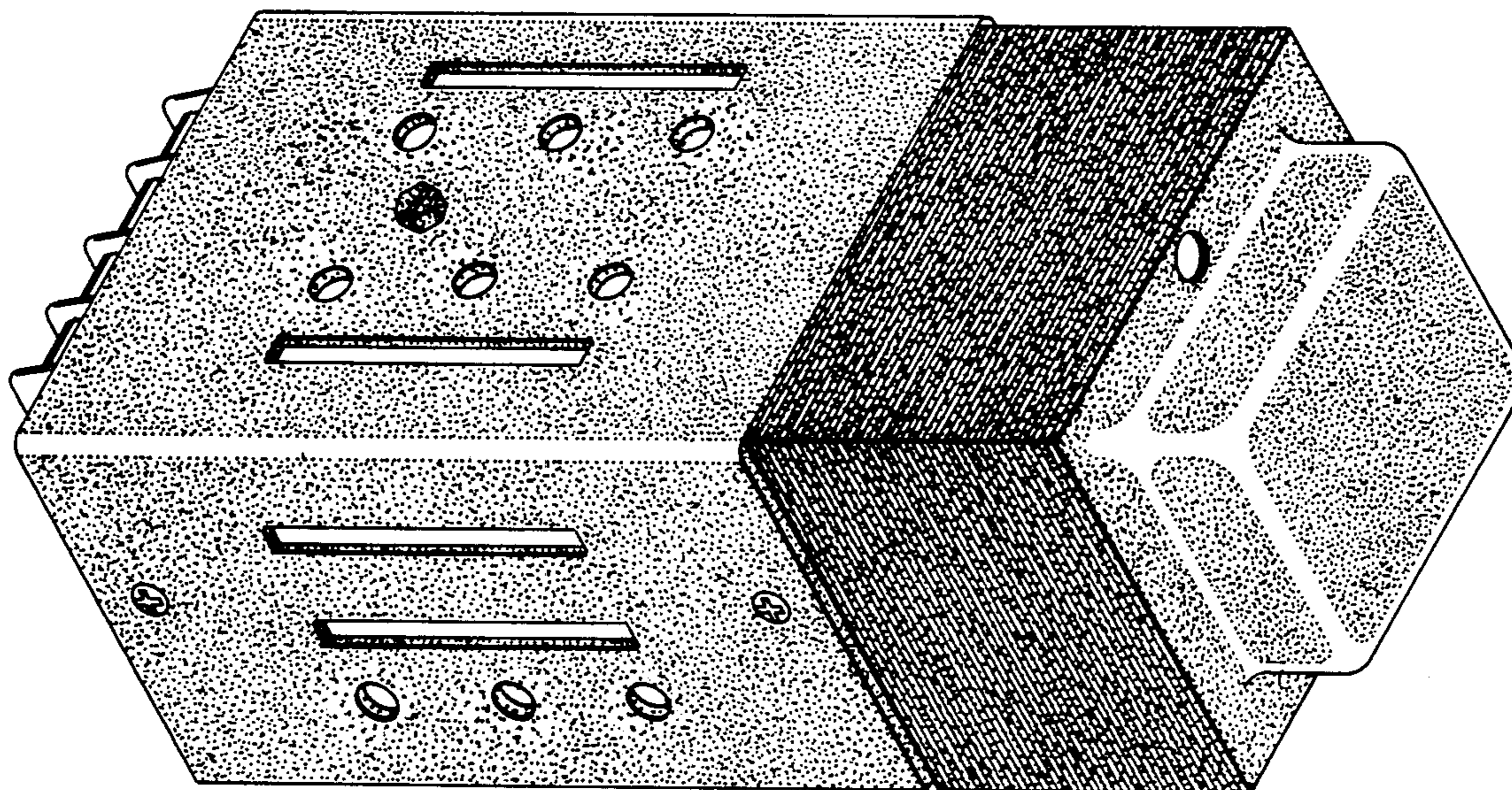


FIG. 2

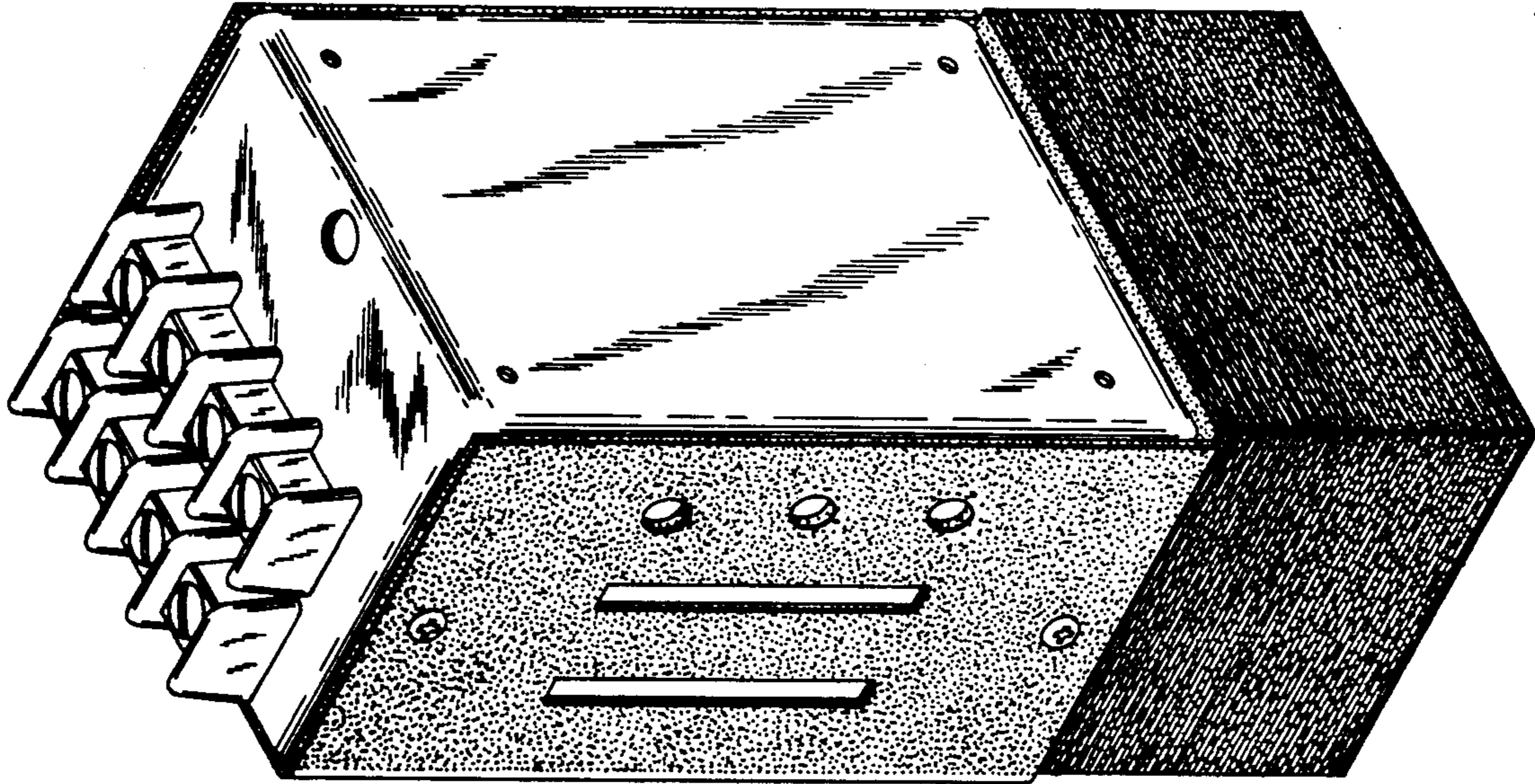


FIG. 3

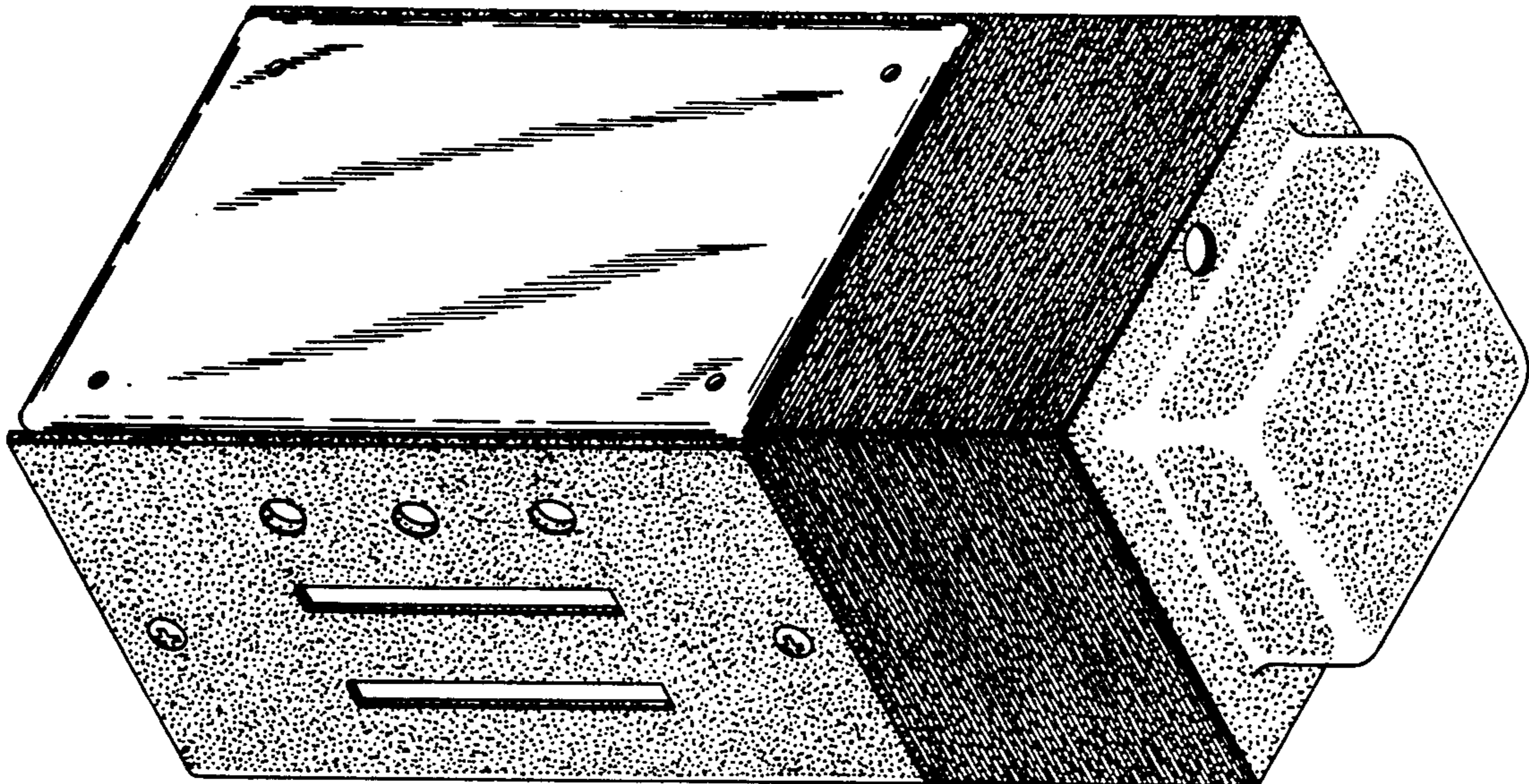


FIG. 4